

PATENT

IN THE UNITED STATES PATENT OFFICE

Serial No.: Unassigned

Filed: Herewith

For: INSERT-MOLDABLE HEAT SPREADER, SEMICONDUCTOR DEVICE USING SAME, AND
METHOD FOR MANUFACTURING SUCH SEMICONDUCTOR DEVICE

Inventor: Masahiro Yonemochi

Atty Doc. No.: 39-02



INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In the interest of full disclosure, the following items are herewith identified in Form PTO-1449 and a copy of the same is hereby provided, for the convenience of the U.S. Patent and Trademark Office.

This Information Disclosure Statement is being filed before the mailing date of the first official action.

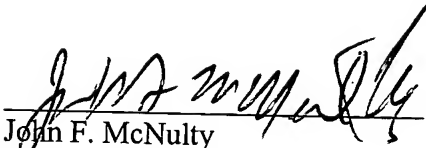
U.S. PATENTS

(AA) USP 5,216,278, dated June 1, 1993.

FOREIGN PATENTS

(AB) JP-A-7-321246, Dated December 8, 1995. For relevance see English abstract.

Respectfully submitted,



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IDS.

(Use several sheets if necessary)

39-02

NA

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U.S. PATENT DOCUMENTS

U.S. POSTAL SERVICE
10/079864
02/21/03

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

DATE CONSIDERED

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